Record of Letter Ballot Review by TC Chapter for Procedural Review

Region/Locale: Japan

Global Technical Committee: Silicon Wafer

TC Chapter Cochairs: T. Nakai /SUMCO, N. Kawai /Meiji University

Standards Staff: J. Collins

	Scheduled in Background Statement	Actual
Date	12/14/2017	12/14/2017
Location	Tokyo Big Sight, Tokyo Japan	Tokyo Big Sight, Tokyo Japan
Reason for Change of Date and/or Location (if changed)		

Note: See Regulations ¶ 9.5 Exception for allowable reason to change.

I. Document Number and Title

Document Number	Document Title
6279	REAPPROVAL OF SEMI MF525-0312
	TEST METHOD FOR MEASURING RESISTIVITY OF
	SILICON WAFERS USING A SPREADING
	RESISTANCE PROBE

II. Tally

Standards staff to fill in.

Voting Tally: As-cast tally after close of voting period

Note: A minimum of 60% of the Voting Interests that have TC Members within the global technical committee that issued the Letter Ballot must return Votes. (*Regulations* ¶ 9.7.1.1)

Voting Tally (with example values):

Returned Votes		Distribution		Return Rate	
57	÷	95	=	60.0%	≥60%
25					
0		Total	Votei	rs with Rejects	0
33					
	25	25	0 Total	0 Total Votes	0 Total Voters with Rejects

Note: See Regulations § 3.2.1 for definition of Voting Interest.

III. Rejects: No Rejects

IV. Other Technical Issues: None

Note: TC Chapter may choose to address a technical issue that is not part of a Negative received on a Letter Ballot (i.e., a Comment or a reason not addressed by a Vote response) by handling it as a Negative and finding it related and technically persuasive. The TC Chapter may then fail the Document or address such technical issue by using the procedure defined in *Regulations* § 9.6.4.3 to make a technical change to the Document. (*Regulations* ¶ 9.6.2.4.5)

V. Comments: No comments

VI. Editorial Changes Other than Those Voted on in § V: None

Original section/paragraph number and at least one full sentence are required in "FROM" and "TO" fields.

VII. Approval Conditions Check

VII. - (i). Approval Rate

APPROVAL CONDITION 1: All Negatives have been discussed and were withdrawn, found not related, found not persuasive, or addressed by a technical change. (*Regulations* ¶ 9.7.1.2)

APPROVAL CONDITION 2: At least 90% of the sum of valid Voting Interest Accept and Voting Interest Reject Votes must be Accept. (*Regulations* ¶ 9.7.1.3)

Note: If both approval conditions are not satisfied, the Document fails.

		Accepts		(Accepts + Valid Rejects)			
Approval Rate	=	33	/	33	=	100.0%	≥90%

VII. – (ii) Approval Level (check one)

Note: See *Regulations* § 9.7.2 for further information.

X

Globally Approved (No Ratification Ballot needed):

The Letter Ballot meets the Letter Ballot approval conditions for the global technical committee.



The Letter Ballot meets the Letter Ballot approval conditions for the TC Chapter and a Ratification Ballot will be issued to validate technical changes.

VIII. Safety Check

Note: See Regulations § 15 for further information.



			ety Document, when all safety-related information is removed, the Document is sound and complete. ($Regulations$ ¶ 8.7.2)			
Safety Checklist (<i>Regulations</i> ¶ 15.3) is complete and has been included with the Docume throughout the balloting process. (<i>Regulations</i> ¶ 15.1.2)						
Motion by/2 nd by		oy/2 nd by	Ryuji Takeda (GlobalWafers Japan)/ Tsuyoshi Otsuki (SEH)			
Discussion		ssion	None			
Vote		ote	11 Y-0 N; Motion passed			

IX. Intellectual Property (IP) Check

Note: This Letter Ballot may cover all or part of a Standard or Safety Guideline. This IP check applies to the entire Standard or Safety Guideline. See *Regulations* § 16 for further information.

х	mate	The TC Chapter meeting chair asked those participating, if they were aware of any potentially material patented technology or copyrighted items* in the Standard or Guideline. (<i>Regulations</i> ¶ 8.8.1)									
	Х		otentially m righted iten		patented technology or reproduction of nown.	GO TO SECTION X.					
		copy copy	Potentially material patented technology or reproduction of copyrighted items is known, but a Letter of Assurance (LOA) or copyright release letter for such items has been obtained or presented to the TC Chapter.								
		use (of such ma	terials i	s technically justified by the TC Chapter, but a	ology or reproduction of copyrighted items is known and justified by the TC Chapter, but an LOA or copyright s) has NOT been obtained or presented to the TC Chapter.					
	N		Ask ISC f	or spec	or special permission to publish.						
	Motion		Quit activ	ity.	ty.						
	'n		Wait for L	.OA for	patented technology or release of copyrighted	d items.					
	Mot	ion by	y/2 nd by								
		Discus	sion	XXXX							
	Vote			XX Y-XX N							
	Final Action				Motion passed						
					Motion failed						

^{*} Note: Such potentially material patented technology or copyrighted items might have become known since the Standard or Safety Guideline was last reviewed, or might become relevant due to this Letter Ballot.

X. Action for This Document

Ma	X	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.								
			s Document passed TC Chapter review with editorial changes and will be forwarded to the CA&R SC for procedural review.							
Motion		editorial ch	This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.							
		This Docui	men	t failed TC Chapter review and will be returned to the TF for rework.						
		This Document failed TC Chapter review and work will be discontinued.								
	Motion by/ 2 nd by		Ry	uji Takeda (GlobalWafers Japan)/ Tsuyoshi Otsuki (SEH)						
	Discussion Vote Final Action		No	ne						
			11	Y-0 N						
-			Χ	Motion passed						
1			Motion failed							

Standards staff to record the result of the A&R procedural review here:

		Approved for publication
A&R		Approved pending acceptance of the Ratification Ballot
Aak		Not approved
	Re	eason: